

PolyZen

Polymer Enhanced Zener Diode Micro-Assemblies

PRODUCT: ZEN056V230A16LS

DOCUMENT: SCD27327

REV LETTER: F

REV DATE: JULY 26, 2016

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Specification Status: Released



GENERAL DESCRIPTION

Littelfuse PolyZen devices are polymer enhanced, precision Zener diode microassemblies. They offer resettable protection against multi-Watt fault events without the need for multi-Watt heat sinks.

The Zener diode used for voltage clamping in a PolyZen micro-assembly was selected due to its relatively flat voltage vs current

response. This helps improve output voltage clamping, even when input voltage is high and diode currents are large.

An advanced feature of the PolyZen micro-assembly is that the Zener diode is thermally coupled to a resistively non-linear, polymer PTC (positive temperature coefficient) layer. This PTC layer is fully integrated into the device, and is electrically in series between V_{IN} and the diode clamped V_{OUT} .

This advanced PTC layer responds to either extended diode heating or overcurrent events by transitioning from a low to high resistance state, also known as" tripping". A tripped PTC will limit current and generate voltage drop. It helps to protect both the Zener diode and the follow on electronics and effectively increases the diode's power handling capability.

The polymer enhanced Zener diode helps protect sensitive portable electronics from damage caused by inductive voltage spikes, voltage transients, incorrect power supplies and reverse bias. These devices are particularly suitable for portable electronics and other low-power DC devices.

BENEFITS

- Stable Zener diode helps shield downstream electronics from overvoltage and reverse bias
- Trip events shut out overvoltage and reverse bias sources
- Analog nature of trip events minimizes upstream inductive spikes
- Minimal power dissipation requirements
- Single component placement

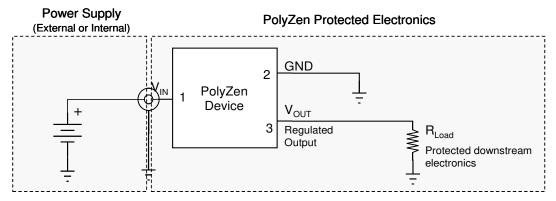
FEATURES

- Overvoltage transient suppression
- Stable Vz vs fault current
- Time delayed, overvoltage trip
- Time delayed, reverse bias trip
- Multi-Watt power handling capability
- Integrated device construction
- RoHS Compliant

TARGET APPLICATIONS

- DC power port protection in portable electronics
- DC power port protection for systems using barrel jacks for power input
- Internal overvoltage & transient suppression
- DC output voltage regulation

TYPICAL APPLICATION BLOCK DIAGRAM





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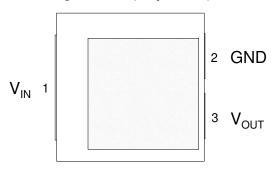
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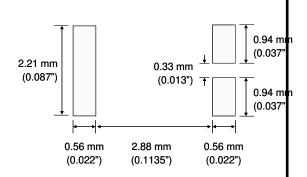
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CONFIGURATION INFORMATION

Pin Configuration (Top View)



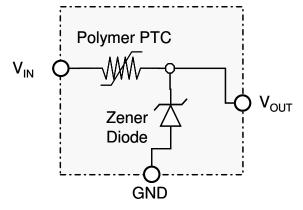
Recommended Pad Dimensions



PIN DESCRIPTION

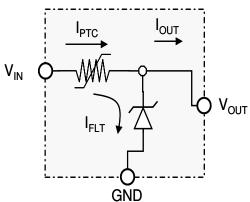
Pin Number	Pin Name	Pin Function
1	V _{IN}	V _{IN} . Protected input to Zener diode.
2	GND	GND
3	Vout	Vour. Zener regulated voltage output

BLOCK DIAGRAM



DEFINITION of TERMS

I _{PTC}	Current flowing through the PTC portion of the circuit				
I _{FLT}	RMS fault current flowing through the diode				
Іоит	Current flowing out the Vout pin of the device				
Trip Event	A condition where the PTC transitions to a high				
	resistance state, thereby significantly limiting IPTC				
	and related currents, and significantly increasing				
	the voltage drop between V _{IN} and V _{OUT} .				
Trip	Time the PTC portion of the device remains both				
Endurance	powered and in a tripped state.				





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GENERAL SPECIFICATIONS

Operating Temperature -40° to +85°C Storage Temperature -40° to +85°C

ELECTRICAL CHARACTERISTICS^{1-3, 11} (Typical unless otherwise specified)

V _z ⁴ (V)		I _{zt} ⁴ I _{HOLD} ⁵		Leakage Current		R Typ⁵	R _{1Max} ⁷	V _{Int} Max ⁸ (V)		I _{FLT} Max ⁹		Tripped Power Dissipation ¹⁰ Max		
Min	Тур	Max	(A)	[@] 20ºC (A)	Test Voltage	Max Current (mA)	(Ohms)	(Ohms)	V _{INT} Max (V)	Test Current (A)	I _{FLT} Max (A)	Test Voltage (V)	Value (W)	Test Voltage (V)
5.45	5.6	5.75	0.1	2.3	5.25	10	0.04	0.06	16V	5A	+5 -40	+16 -12V	1.0	16

Note 1: Electrical characteristics determined at 25°C unless otherwise specified.

Note 2:This device is intended for limited fault protection. Repeated trip events or extended trip endurance can degrade the device and may affect performance to specifications. Performance impact will depend on multiple factors including, but not limited to, voltage, trip current, trip duration, trip cycles, and circuit design. For details or ratings specific to your application contact Littelfuse Circuit Protection directly.

Note 3:Specifications developed using 1.0 ounce 0.045" wide copper traces on dedicated FR4 test boards. Performance in your application may vary.

Note 4:Izt is the current at which Vz is measured (Vz = Vout). Additional Vz values are available on request.

Note 5:I_{HOLD}: Maximum steady state I_{PTC} (current entering or exiting the V_{IN} pin of the device) that will not generate a trip event at the specified temperature. Specification assumes I_{FLT} (current flowing through the Zener diode) is sufficiently low so as to prevent the diode from acting as a heat source. Testing is conducted with an "open" Zener.

Note 6:R Typ: Resistance between V_{IN} and V_{OUT} pins during normal operation at room temperature.

Note 7:R_{1Max}: The maximum resistance between V_{IN} and V_{OUT} pins at room temperature, one hour after 1st trip or after reflow soldering.

Note 8: V_{INT} Max: V_{INT} Max relates to the voltage across the PPTC portion of the PolyZen device (V_{IN} - V_{OUT}). V_{INT} Max is defined as the voltage (V_{IN} - V_{OUT}) at which typical qualification devices (98% devices, 95% confidence) survived at least 100 trip

cycles and 24 hours trip endurance at the specified voltage $(V_{IN}-V_{OUT})$ and current (I_{PTC}) . V_{INT} Max testing is conducted using a "shorted" load $(V_{OUT} = 0V)$. V_{INT} Max is a survivability rating, not a performance rating.

Note 9:I_{FLT} Max: I_{FLT} Max relates to the stead state current flowing through the diode portion of the PolyZen device in a fault condition, prior to a trip event. I_{FLT} Max is defined as the current at which typical qualification devices (12 parts per lot from 3 lots) survived 100 test cycles. RMS fault currents above I_{FLT} Max may permanently damage the diode portion of the PolyZen device. Testing is conducted with \underline{NO} load connected to V_{OUT}, such that I_{OUT} = 0. "Test voltage" is defined as the voltage between V_{IN} to GND and includes the PolyZen Diode drop. Specification is dependent on the direction of current flow through the diode.

IFLT Max is a survivability rating, not a performance rating.

Note 10:The power dissipated by the device when in the "tripped" state, as measured on Littelfuse test boards (see note 3).

Note 11:Specifications based on limited qualification data and subject to change.



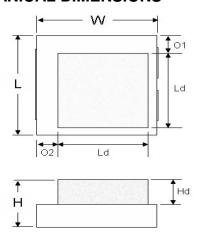
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MECHANICAL DIMENSIONS



		Min	Typical	Max
Length	L	3.85 mm (0.152")	4 mm (0.16")	4.15 mm (0.163")
Width	W	3.85 mm (0.152")	4 mm (0.16")	4.15 mm (0.163")
Height	Н	1.4mm (0.055")	1.7 mm (0.067")	2.0 mm (0.081")
Length Diode	Ld	-	3.0 mm (0.118")	-
Height Diode	Hd	-	1.0 mm (0.039")	-
Offset	01	-	0.6 mm (0.024")	-
Offset	O2	-	0.7 mm (0.028")	-

SOLDER REFLOW RECOMMENDATIONS:

Classification Reflow Profiles						
Profile Feature	Pb-Free Assembly					
Average Ramp-Up Rate (Tsmax to Tp)	3° C/second max.					
Preheat						
Temperature Min (Tsmin)	150 °C					
Temperature Max (Tsmax)	200 °C					
Time (tsmin to tsmax)	60-180 seconds					
Time maintained above:						
Temperature (TL)	217 °C					
• Time (tL)	60-150 seconds					
Peak/Classification Temperature						
(Tp)	260 °C					
Time within 5 °C of actual Peak						
Temperature (tp)	20-40 seconds					
Ramp-Down Rate	6 °C/second max.					
Time 25 °C to Peak Temperature	8 minutes max.					



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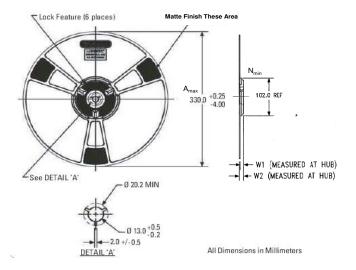
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PACKAGING

Packaging	Tape & Reel	Standard Box
ZENXXXVXXXAXXLS	3,000	15,000

Reel Dimensions for PolyZen Devices

 $A_{max} = 330$ $N_{min} = 102$ $W_1 = 8.4$ $W_2 = 11.1$





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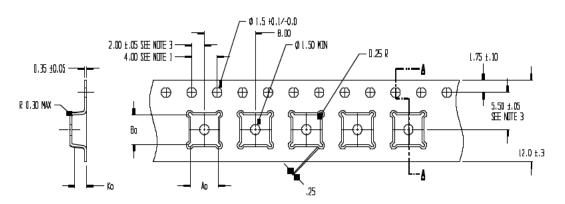
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Taped Component Dimensions for PolyZen Devices



Aa = 4.35 NOTES:

Bo = 4.35 I. 10 SPROCKET HOLE PITCH CLMULATIVE TOLERANCE ±0.2

Ko = 2.30 2. CAMBER IN COMPLIANCE VITH EIA 481

3. POCKET POSITION RELATIVE TO SPROCKET HOLE MEASURED AS TRUE POSITION OF POCKET, NOT POCKET HOLE

TYPICAL CHARACTERISTICS



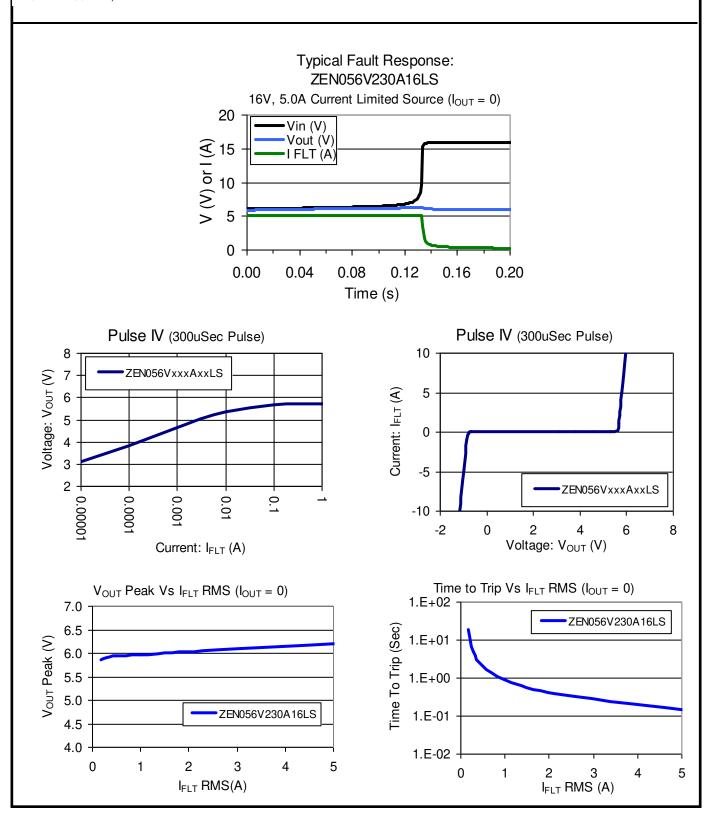
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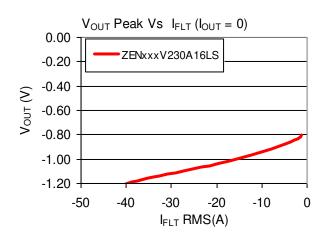
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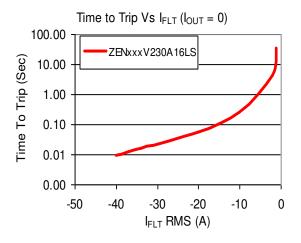
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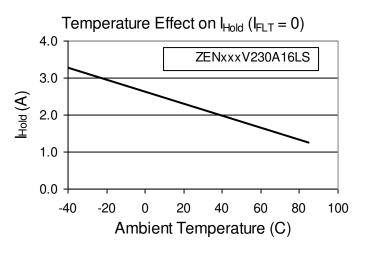
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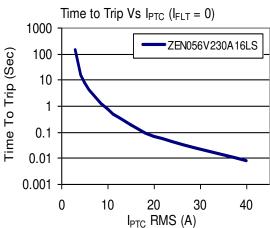
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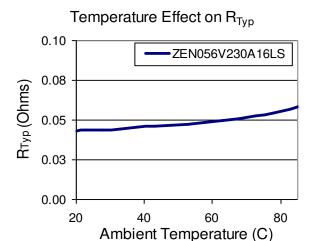
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Materials Information

ROHS Compliant

Directive 2002/95/EC Compliant **ELV Compliant**

Directive 2000/53/EC Compliant

Pb-Free



Halogen Free*



* Halogen Free refers to: Br≤900ppm, Cl≤900ppm, Br+Cl≤1500ppm.

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